TOSHIBA Photocoupler GaAs Ired & Photo-Transistor

TLP130

Programmable Controllers AC / DC-Input Module Telecommunication

The TOSHIBA mini flat coupler TLP130 is a small outline coupler, suitable for surface mount assembly.

TLP130 consists of a photo transistor, optically coupled to two gallium arsenide infrared emitting diode connected inverse parallel, and operate directly by AC input current.

• Collector-emitter voltage: 80V(min.)

• Current transfer ratio: 50%(min.)

Rank GB: 100%(min.)

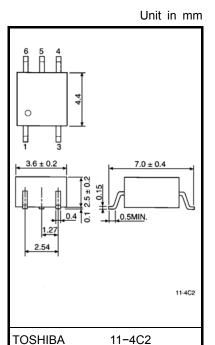
• Isolation voltage: 3750Vrms(min.)

• UL recognized: UL1577, file no.E67349

• Current transfer ratio

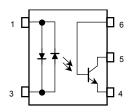
Classi– fication	Current Tra	Marking Of		
	$I_F = 5mA, V_{CE} = 5V, Ta = 25^{\circ}C$		Classification	
lication	Min.	Max.	Classification	
Standard	50	600	Blank, Y, GR, GB	
Rank GB	100	600	GB,GR	

(Note) Application type name for certification test, please use standard product type name, i.e. TLP130(GB): TLP130



Weight: 0.09 g (typ.)

Pin Configurations (top view)



- 1 : Anode, Cathode
- 3 : Cathode, Anode
- 4 : Emitter
- 5 : Collector
- 6 : Base

Absolute Maximum Ratings (Ta = 25°C)

	Characteristic		Symbol	Rating	Unit
	Forward current		I _{F(RMS)}	50	mA
Ω	Forward current derating (Ta≥53°C)		ΔI _F / °C	-0.7	mA / °C
LED	Peak forward current (100µs pulse,100pps)		IFP	1	Α
	Junction temperature		Tj	125	°C
	Collector-emitter voltage		V _{CEO}	80	V
	Collector-base voltage		V_{CBO}	80	V
	Emitter-collector voltage		V_{ECO}	7	\
'n	Emitter-base voltage		V _{EBO}	7	V
Detector	Collector current		Ic	50	mA
Ď	Peak collector current (10ms pulse,100pps)		I _{CP}	100	mA
	Power dissipation		PC	150	mW
	Power dissipation derating (Ta≥25°C)		ΔP _C / °C	-1.5	mW / °C
	Junction temperature		Tj	125	°C
Stor	rage temperature range		T _{stg}	-55~125	°C
Оре	erating temperature range		T _{opr}	-55~100	°C
Lead soldering temperature (10s)			T _{sol}	260	°C
Total package power dissipation			PT	200	mW
Total package power dissipation derating (Ta≥25°C)			ΔP _T / °C	-2.0	mW / °C
Isola	ation voltage (AC, 1min., RH ≤ 60%)	(Note 1)	BVS	3750	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

(Note 1) Device considered a two terminal device: Pins 1 and 3 shorted together and pins 4, 5 and 6 shorted together.

Recommended Operating Conditions

Characteristic	Symbol	Min.	Тур.	Max.	Unit
Supply voltage	V _{CC}	_	5	48	V
Forward current	I _{F(RMS)}	_	16	25	mA
Collector current	IC	_	1	10	mA
Operating temperature	T _{opr}	-25	-	85	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

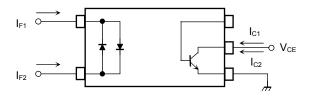
Individual Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min.	Тур.	Max.	Unit
LED	Forward voltage	V _F	I _F = ±10mA	1.0	1.15	1.3	V
۳	Capacitance	C _T	V = 0, f = 1MHz	_	60	_	pF
	Collector–emitter breakdown voltage	V _{(BR)CEO}	I _C = 0.5mA	80	_	_	V
	Emitter-collector breakdown voltage	V _{(BR)ECO}	I _E = 0.1mA	7	_	_	V
	Collector-base breakdown voltage	V _{(BR)CBO}	I _C = 0.1mA	80	_	_	V
	Emitter-base breakdown voltage	V _{(BR)EBO}	I _E = 0.1mA	7	_	_	V
Detector	Collector dark current	lone	V _{CE} = 48V	_	10	100	nA
Det	Collector dark current	ICEO	V _{(BR)EBO} I _E = 0.1mA	_	2	50	μΑ
	Collector dark current	ICER	V_{CE} = 48V, Ta = 85°C R _{BE} = 1M Ω	_	0.5	10	μΑ
	Collector dark current	I _{CBO}	V _{CB} = 10V	_	0.1	_	nA
	DC forward current gain	h _{FE}	V _{CE} = 5V, I _C = 0.5mA		400		_
	Capacitance collector to emitter	C _{CE}	V = 0 , f = 1MHz	_	10	_	pF

Coupled Electrical Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Current transfer ratio	Ic/le	$I_F = \pm 5$ mA, $V_{CE} = 5$ V	50	_	600	%
Current transfer ratio	IC7 IF	Rank GB	100	_	600	70
Saturated CTR	I _C / I _{F(sat)}	I _F = ±1mA, V _{CE} = 0.4V	_	%		
Saturated CTR	iC7 iF(sat)	F(sat) Rank GB		_	_	70
Base photo-current	I _{PB}	$I_F = \pm 5$ mA, $V_{CB} = 5$ V		10	_	μΑ
				_	0.4	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 0.2 \text{mA}, I_F = \pm 1 \text{mA}$		0.2	_	V
Saturation voltage		Rank GB	_	_	0.4	
Off-state collector current	I _{C(off)}	$I_F = \pm 0.7 \text{mA}, V_{CE} = 48 \text{V}$		1	10	μΑ
CTR symmetry	I _{C(ratio)}	$I_C(I_F = -5mA) / I_C(I_F = 5mA)$ (Note 2)	0.33	_	3	_

(Note 2)
$$I_{C(ratio)} = \frac{I_{C2}(I_F = I_{F2}, V_{CE} = 5V)}{I_{C1}(I_F = I_{F1}, V_{CE} = 5V)}$$



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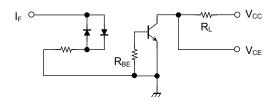
Isolation Characteristics (Ta = 25°C)

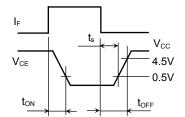
Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Capacitance input to output	CS	V _S =0, f=1MHz	_	0.8	_	pF
Isolation resistance	R _S	V _S =500V	5×10 ¹⁰	10 ¹⁴	_	Ω
		AC, 1minute	3750	_	_	Vrms
Isolation voltage	BV_S	AC, 1second, in oil	_	10000	_	VIIIIS
		DC, 1 minute, in oil	_	10000	1	Vdc

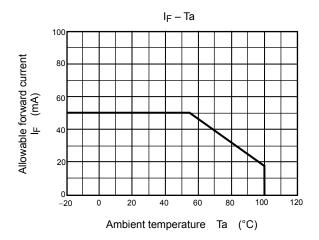
Switching Characteristics (Ta = 25°C)

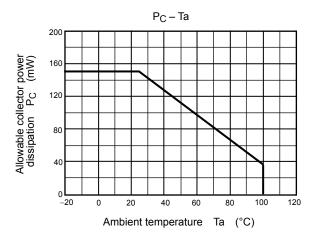
Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Rise time	t _r		_	2	_	.10
Fall time	t _f	V _{CC} = 10V, I _C = 2mA	_	3	_	
Turn-on time	t _{on}	$R_L = 100\Omega$	_	3	_	μs
Turn-off time	t _{off}		_	3	_	
Turn-on time	t _{ON}	$R_L = 1.9 \text{ k}\Omega$ (Fig.1)	_	2	_	
Storage time	t _S	R _{BE} = OPEN	_	25	_	μs
Turn-off time	t _{OFF}	$V_{CC} = 5 \text{ V}, I_F = \pm 16 \text{mA}$	_	40	_	
Turn-on time	t _{ON}	$R_L = 1.9k\Omega$ (Fig.1) - $R_{BE} = 220k\Omega$ $V_{CC} = 5 \text{ V, I}_F = \pm 16\text{mA}$	_	2	_	
Storage time	t _S		_	20	_	μs
Turn-off time	tOFF		1	30	_	

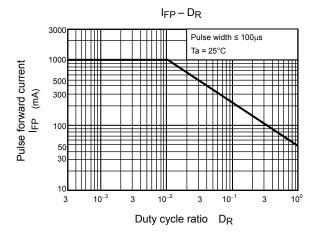
Fig. 1 Switching time test circuit

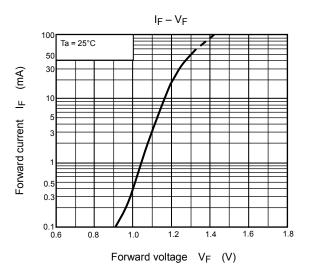


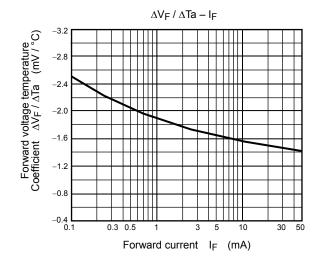


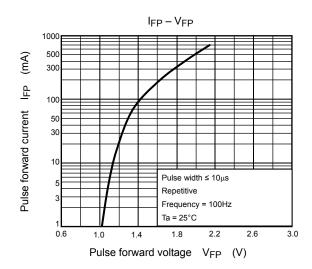




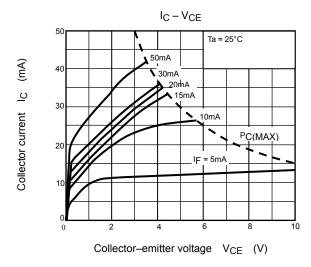


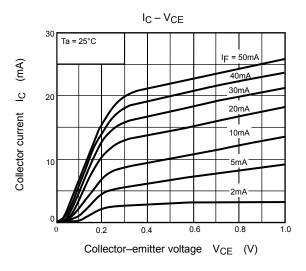


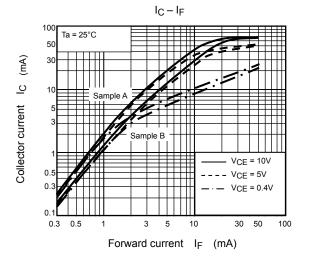


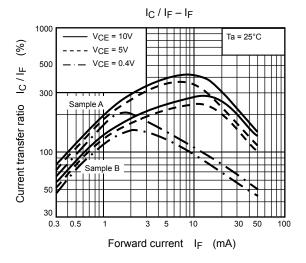


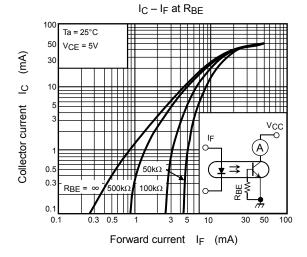
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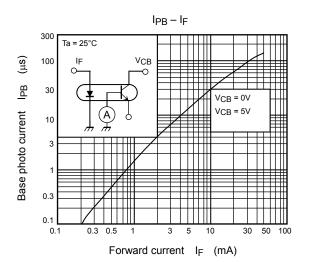


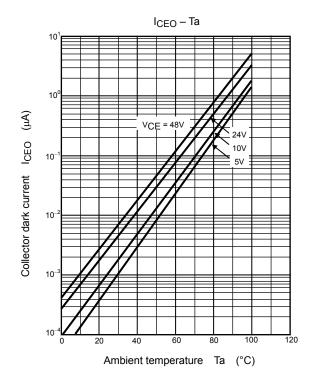


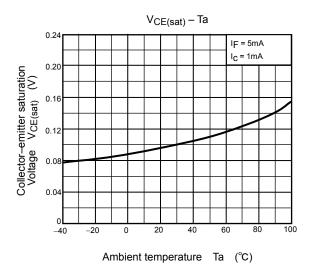


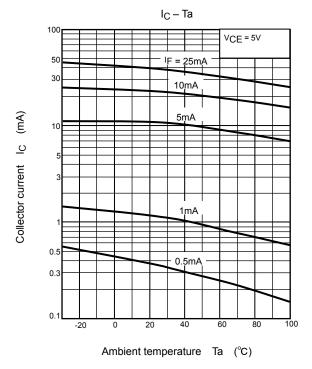


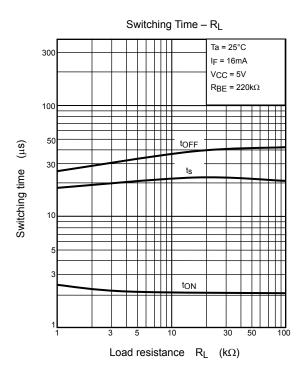


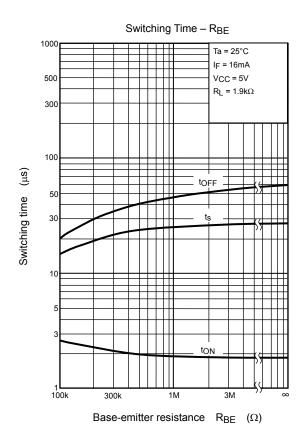


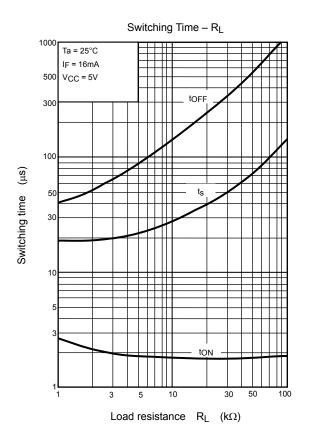












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